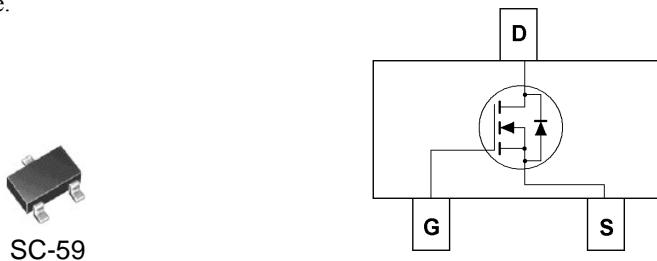


N-Channel Enhancement Mode MOSFET

Feature

- 20V/6A, $R_{DS(ON)} = 35\text{m}\Omega(\text{MAX})$ @ $V_{GS} = 4.5\text{V}$.
 $R_{DS(ON)} = 45\text{m}\Omega(\text{MAX})$ @ $V_{GS} = 2.5\text{V}$.
- Super High dense cell design for extremely low $R_{DS(ON)}$.
- Reliable and Rugged.
- SC-59 for Surface Mount Package.

**Applications**

- LI-ION Protection Circuit

Absolute Maximum Ratings

TA=25°C Unless Otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous	I_D	6	A

Electrical Characteristics

TA=25°C Unless Otherwise noted

Parameter	Symbol	Test Conditions	Min	Typ.	Max	Units
Off Characteristics						
Drain to Source Breakdown Voltage	BVDSS	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	-	-	V
Zero-Gate Voltage Drain Current	IDSS	$V_{DS}=16\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
Gate Body Leakage Current, Forward	IGSSF	$V_{GS}=10\text{V}$, $V_{DS}=0\text{V}$	-	-	100	nA
Gate Body Leakage Current, Reverse	IGSSR	$V_{GS}=-10\text{V}$, $V_{DS}=0\text{V}$	-	-	-100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	0.4	-	1.3	V
Static Drain-source	RDS(ON)	$V_{GS}=4.5\text{V}$, $I_D=6.0\text{A}$	-	28	35	$\text{m}\Omega$
On-Resistance		$V_{GS}=2.5\text{V}$, $I_D=5.2\text{A}$	-	35	45	$\text{m}\Omega$
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Voltage	VSD	$V_{GS}=0\text{V}$, $I_S=1.5\text{A}$			1.2	V

DYNAMIC PARAMETERS						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =8V, f=1MHz		800		pF
Output Capacitance	C _{oss}			155		pF
Reverse Transfer Capacitance	C _{rss}			125		pF
SWITCHING PARAMETERS						
Total Gate Charge	Q _g	V _{GS} =4V, V _{DS} =10V, I _D =4A		11		nC
Gate Source Charge	Q _{gs}			2.2		nC
Gate Drain Charge	Q _{gd}			2.5		nC
Turn-On Delay Time	t _{D(on)}		V _{GS} =4V, V _{DS} =10V, I _D =1A, R _{GEN} =10Ω, R _L =10Ω	18.3		ns
Turn-On Rise Time	t _r			4.8		ns
Turn-Off Delay Time	t _{D(off)}			43.5		ns
Turn-Off Fall Time	t _f			20		ns

**Nanker reserves the right to improve product design, functions and reliability without notice.

Typical Characteristics

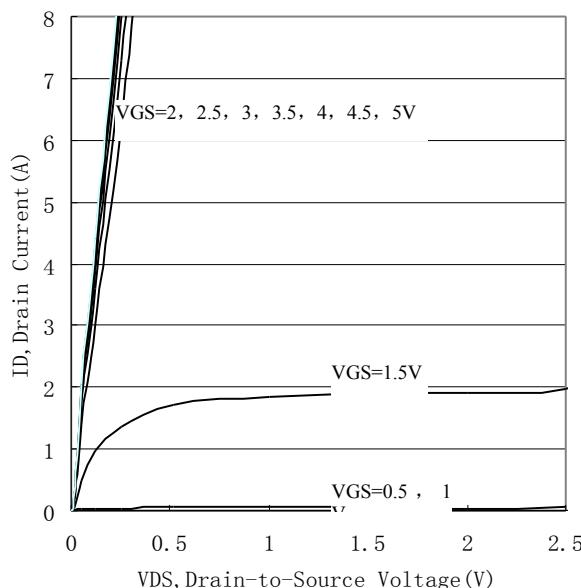


Figure 1. Output Characteristics

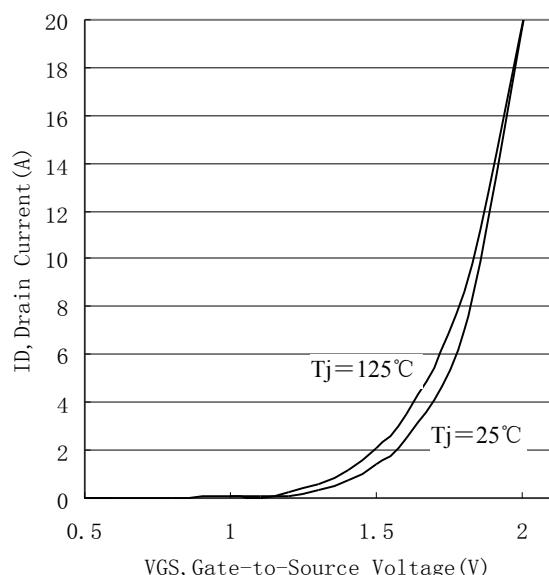


Figure 2. Transfer Characteristics

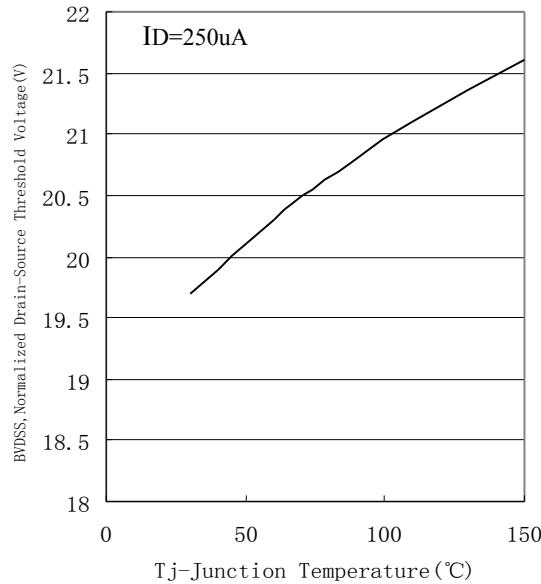


Figure 3. Breakdown Voltage Variation with Temperature

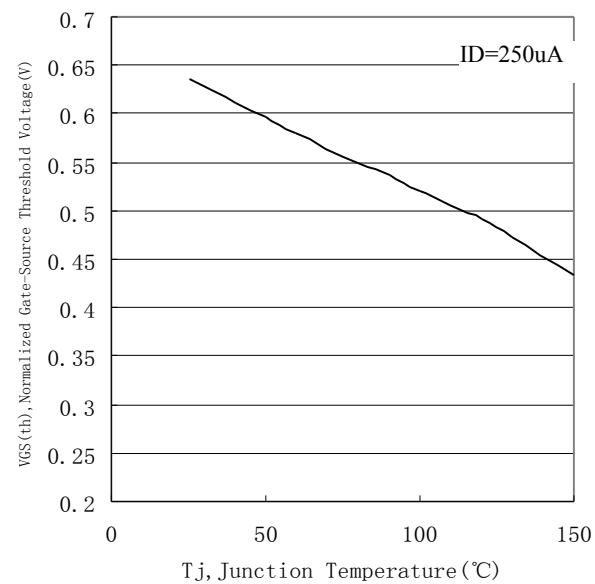


Figure 4. Gate Threshold Variation with Temperature

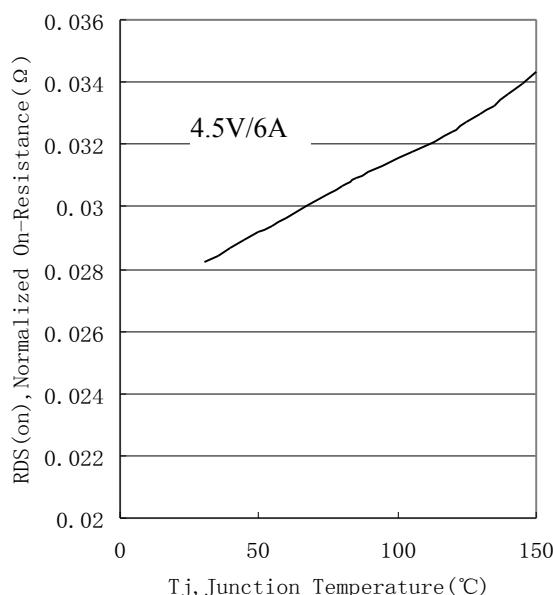


Figure 5. On-Resistance Variation with Temperature

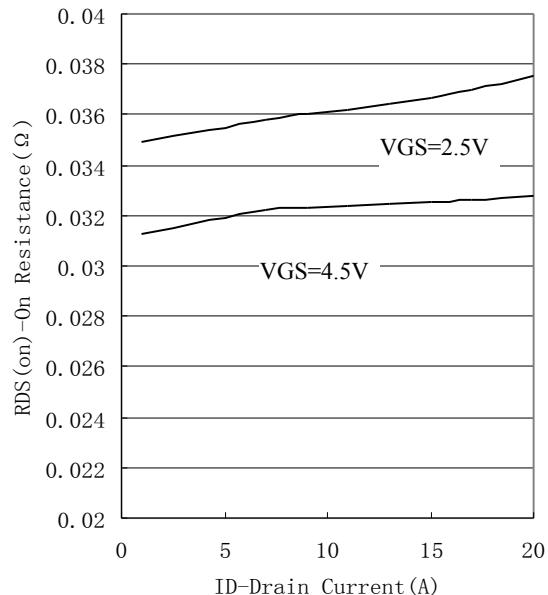


Figure 6. On-Resistance vs. Drain Current

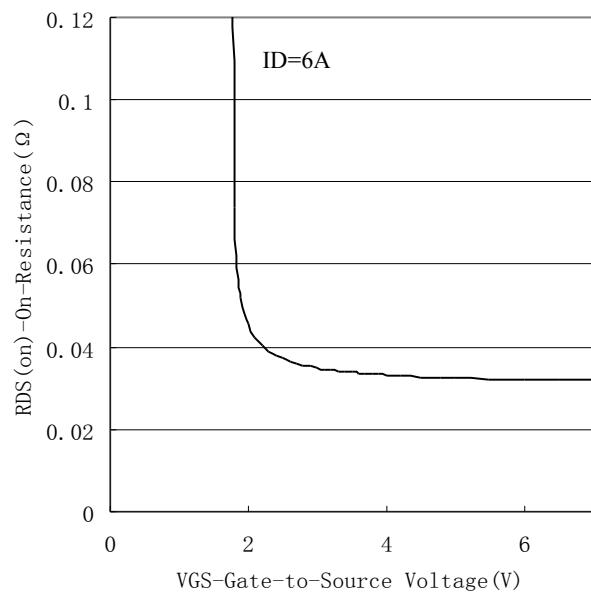


Figure 7 . On-Resistance vs. Gate-to-Source Voltage

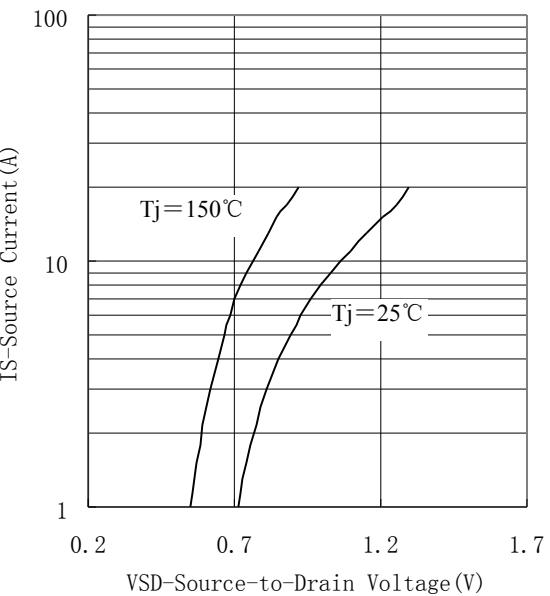


Figure 8 . Source-Drain Diode Forward Voltage

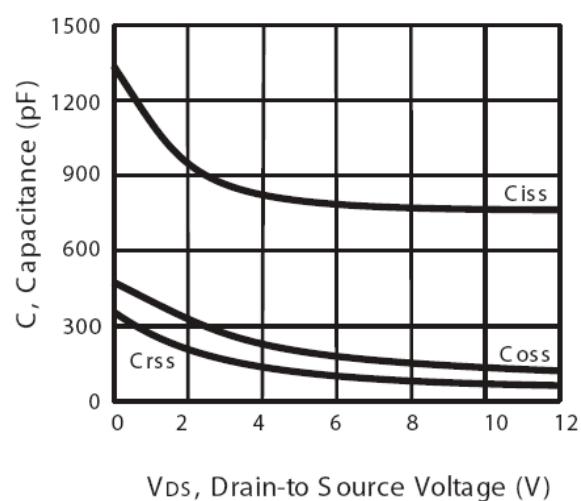


Figure 9. Capacitance

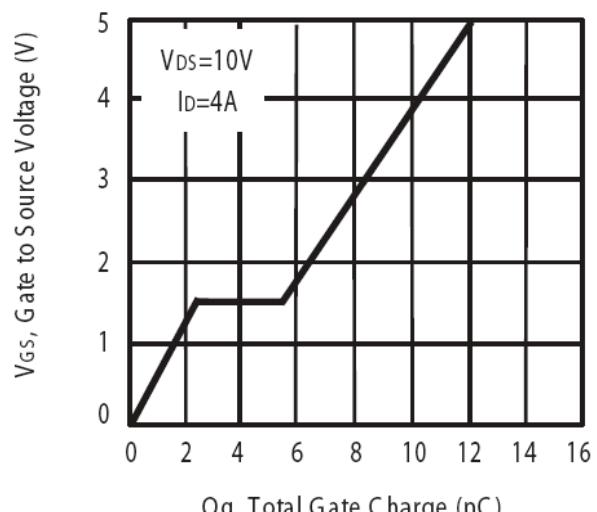


Figure 10. Gate Charge

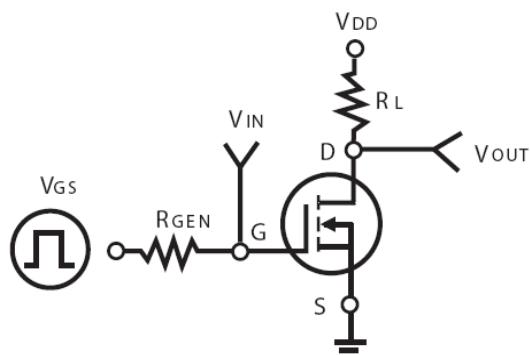


Figure 11. Switching Test Circuit

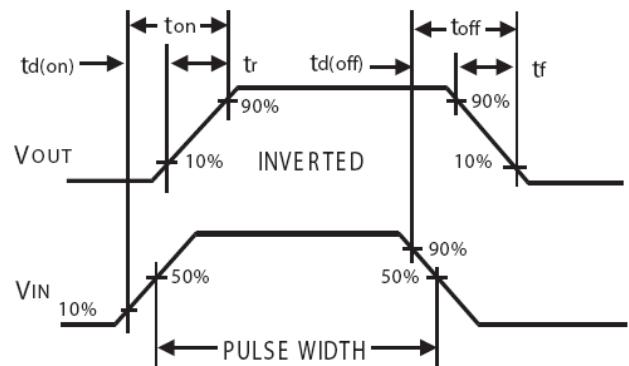
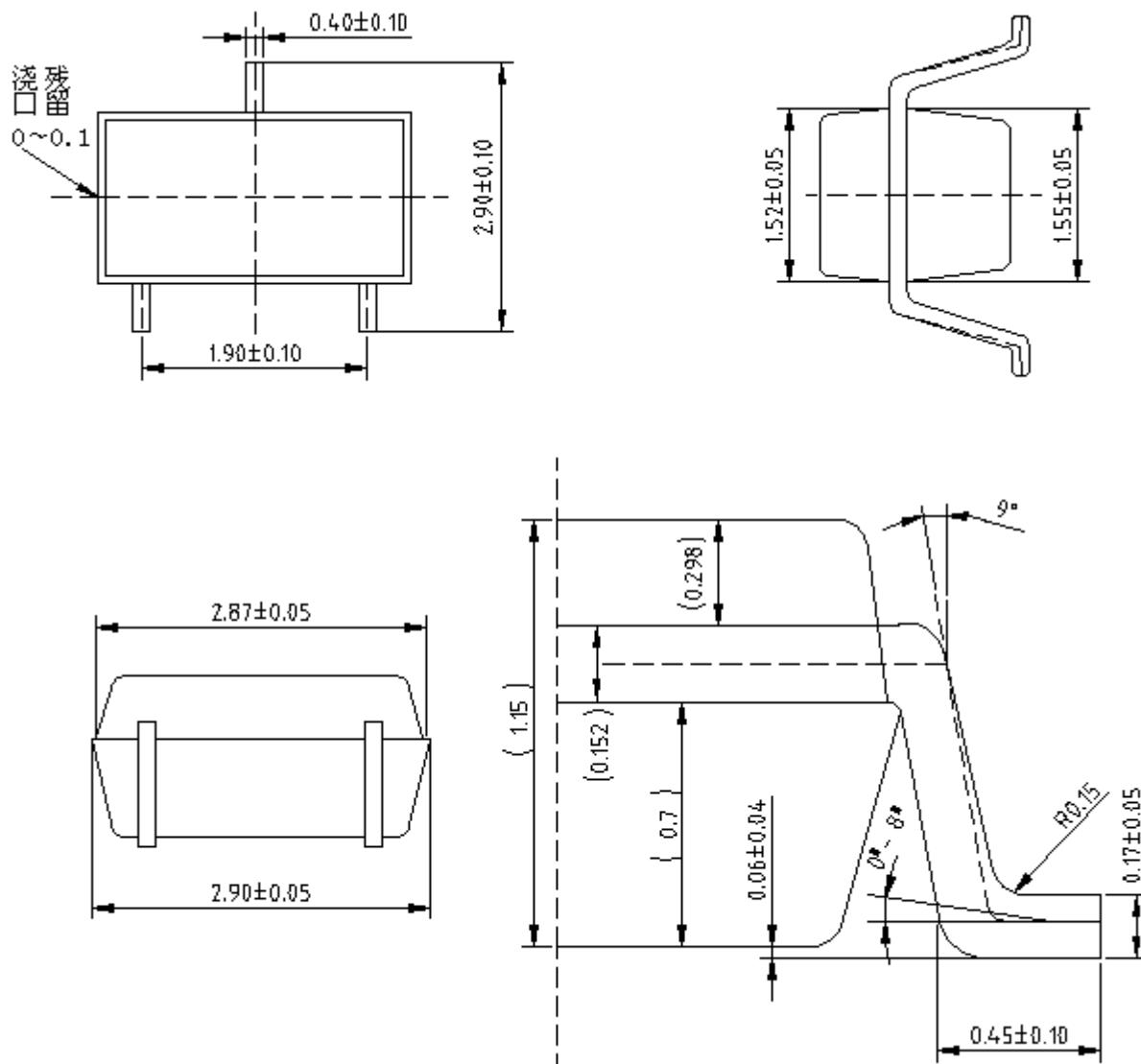
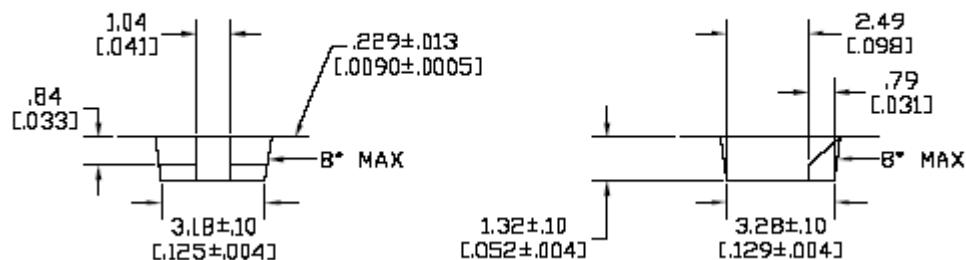
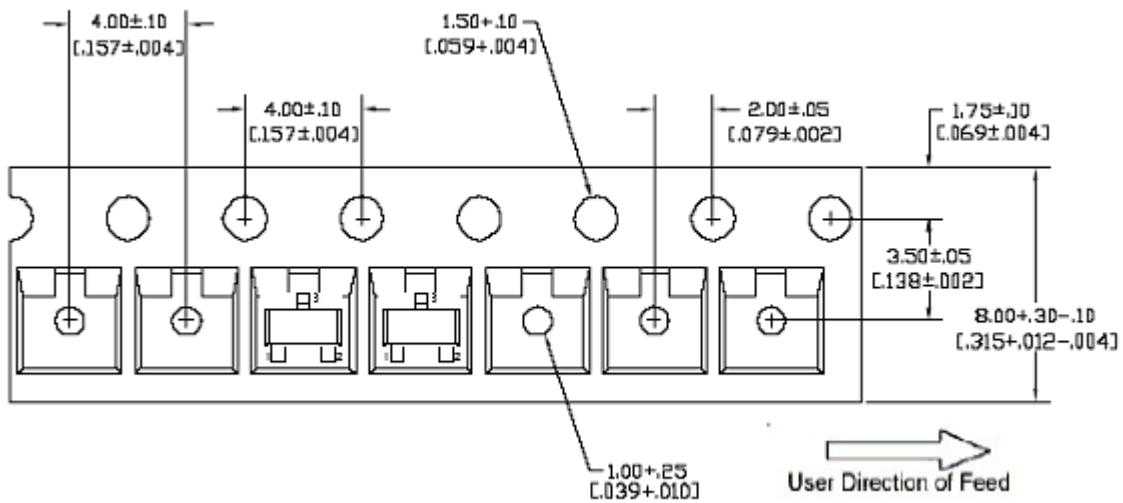


Figure 12. Switching Waveforms

SC-59 Package Outline Dimensions (UNIT: mm)



SC-59 Carrier Tape



SC-59 Carrier Reel

